XILINX®

August 3, 2000

Product Change Notification PCN00003

A change in the die-attach material for all thermally enhanced BGA packages.

Subject: Product Change Notification (PCN00003). "A change in the die-attach material for all thermally enhanced BGA packages.

Products Affected: All packages assembled as SBGA or VBGA.

Change Description: The die-attach material for all thermally enhanced BGA packages is being changed from QMI-595 to Hitachi EN4900 (or AMK-02 - Amkor's internal part number).

Qualification Data: Reference qualification data.

Reason For Change: This change is being made for better product reliability and for process improvement.

Key Dates: Products assembled starting with date code 0044.

Response: No response to this notification is required. Requests for additional data or support should be made within 90 days of notification. Please address any other questions you may have via e-mail at "pcn@xilinx.com", or directly by fax at (408) 559-1368.